

Standard part numbering

Standard devices

Die part numbers are derivative of the die process number, principal device part number, and packing method. For further information on die part numbering, visit Central's bare die webpage.

www.centrasemi.com/baredie

Example:

Small Signal NPN high voltage transistor die, 2N3439, in a chip tray (Waffle) Package.

CP310 - 2N3439 - CT

DEVICE TYPE NUMBER
(10 ALPHA/NUMERIC MAX)

CENTRAL PROCESS NUMBER
(5 - 7 ALPHA/NUMERIC)

CPxxx = Transistor
CPZxx = Zener Diode
CPDxx = Diode
CPQxx = TRIAC
CPSxx = SCR

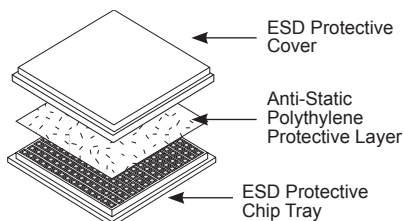
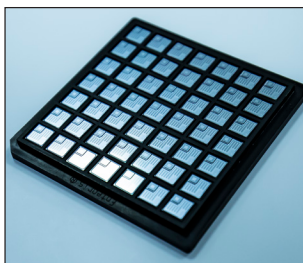
PACKING METHOD

See below for illustrations of each packing method.

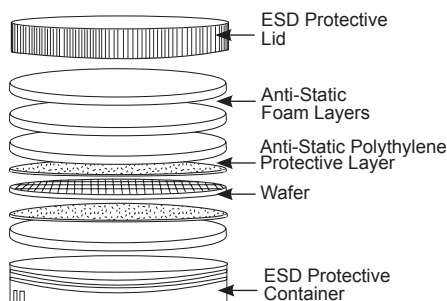
- CM** = Singulated bare die, 100% electrically tested, 100% visually inspected, reject die removed, tray (waffle) package
 - CT** = Singulated bare die, 100% electrically tested, reject die removed, tray (waffle) package
 - WN** = Wafer form, 100% electrically tested, reject die inked
 - WR** = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and plastic ring, reject die inked
 - WS*** = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and metal frame, reject die inked
- *WS is by special order only. Please contact your local Central sales representative.

Packing methods

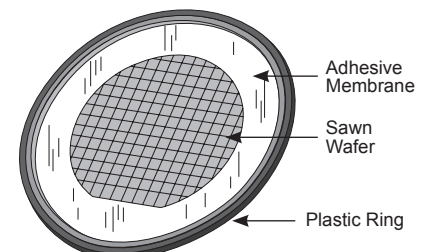
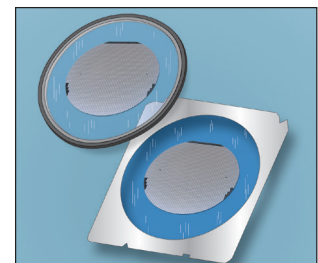
Waffle pack (CM, CT)



Full unsawn wafers (WN)



Sawn wafer on plastic ring (WR) or metal frame* (WS)



Custom & up-screened part numbering

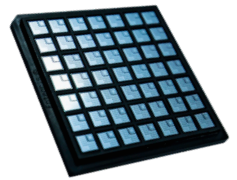
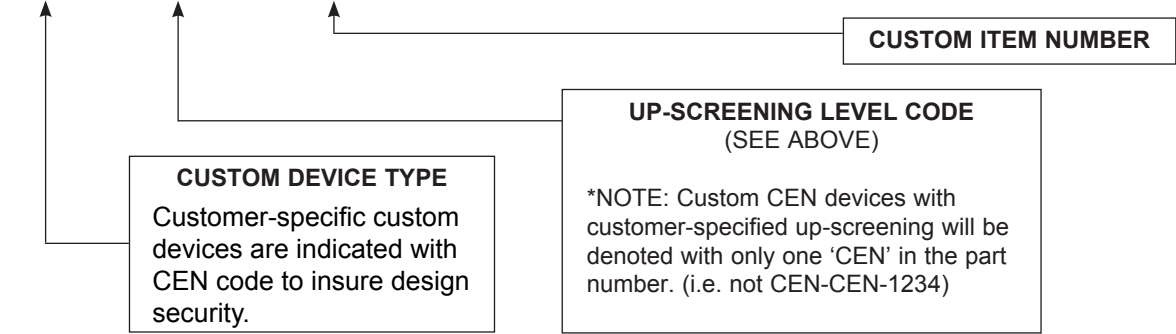
Custom devices

Part numbering for up-screened bare die devices follow the same convention as standard part numbers (see pg. 6), with the addition of one or two character codes to indicate the level of screening.

Example:

Custom device up-screened to MIL-PRF-19500 equivalent or customer defined test specifications.

CEN - KC - 1234



Up-screened devices

Part numbering for up-screened bare die devices follows the same convention as standard part numbers (see pg. 6), with the addition of one or two character codes to indicate the level of screening.

Example:

Zener diode die, up-screened to MIL-PRF-38534 Class H equivalent, 1N4743A, in wafer form on adhesive membrane with plastic ring.

CPZ25 - H - 1N4743A - WR

